



Material Content Data Sheet



Sales Product Name		ICE3RBR0665JZ		Issued		25. September 2017		
MA#		MA001374724						
Package		PG-DIP-7-3		Weight*		645.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.909	0.45	0.45	4509	4509
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75	
	non noble metal	zinc	7440-66-6	0.194	0.03		300	
	non noble metal	iron	7439-89-6	3.872	0.60		6002	
wire	non noble metal	copper	7440-50-8	157.218	24.37	25.01	243695	250072
	noble metal	gold	7440-57-5	0.408	0.06	0.06	633	633
	encapsulation	organic material	carbon black	1333-86-4	2.351	0.36		3645
encapsulation	plastics	epoxy resin	-	63.485	9.84		98405	
	inorganic material	silicondioxide	60676-86-0	404.423	62.69	72.89	626874	728924
leadfinish	non noble metal	tin	7440-31-5	6.540	1.01	1.01	10138	10138
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2471	2471
glue	plastics	epoxy resin	-	0.367	0.06		569	
	noble metal	silver	7440-22-4	1.732	0.27	0.33	2684	3253
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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